

Serial No.: 09/396,352

10/13/2000

DOCKET NO.: NOVA-002-USAP

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Tümay Tümer

Serial No.: 09/396,352

Filed: September 14, 1999

Art Unit: 2736

Examiner: HUANG, S

For: TAG HAVING A SEMICONDUCTOR CHIP AND METHOD OF ATTACHMENT
ARTICLE

TRANSMITTAL

Assistant Commissioner of
Patents and Trademarks
Washington, D.C. 20231
Box: Non-Fee Amendments

Sir: TRANSMITTED HERewith IS

☐ A RESPONSE, ☒ AN AMENDMENT, ☐ AN AMENDMENT AFTER FINAL,

IN THE ABOVE-IDENTIFIED APPLICATION.

☐ Small entity status of this application under 37 CFR §1.9(f) is established
by a verified statement under 37 CFR §1.27

☐ previously submitted.
☐ submitted herewith.

☒ No additional fee is required, as shown below.

CLAIMS PENDING AFTER AMENDMENT		CLAIMS PREVIOUSLY PAID		NEW CLAIMS EXTRA		ADDITIONAL FEES			
						SMALL ENTITY		OTHER THAN SMALL ENTITY	
TOTAL	24	MINUS	25	=	0	x\$9=	0.00	x\$18=	0.00
INDEP	2	MINUS	3	=	0	x40=	0.00	x\$80=	0.00
NEW MULTIPLE DEPENDENT CLAIMS					0	x\$135=	0.00	x\$270=	0.00
AND CLAIMS DEPENDENT THEREON					0	x\$135=	0.00	x\$270=	0.00
TOTAL ADDITIONAL FEE						0.00		0.00	

Serial No.: 09/396,352

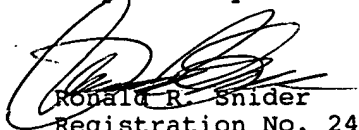
10/13/2000

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☒ X

This amount is believed to be correct, however, the Commissioner is hereby authorized to charge any deficiency or credit any overpayment to Deposit Account No. 19-2816. This authorization applies to both filing fees under 37 CFR §1.16 and processing fees (such as extension of time) under 37 CFR §1.17. A duplicate copy of this transmittal is attached.

Respectfully Submitted,



Ronald R. Snider

Registration No. 24,962

Date: October 13, 2000

Snider & Associates

Ronald R. Snider

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Washington, D.C. 20038-7613

(202) 347-2600

RRS/bam

Serial No.: 09/396,352

10/13/2000

DOCKET NO.: NOVA-002-USA

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Tümay TÜMER

Serial No.: 09/396,352

Filed: September 14, 1999

Art Unit: 2736

Examiner: HUANG, S

For: TAG HAVING A SEMICONDUCTOR CHIP AND METHOD OF ATTACHMENT
ARTICLE

AMENDMENT

Assistant Commissioner of
Patents and Trademarks
Washington, D.C. 20231
Box: Non-Fee Amendments

Sir:

This Amendment is responsive to the Office Action dated July 19, 2000. Claims 1 and 3 - 26 are pending in this application and have been rejected.

Please amend this application as follows:

IN THE SPECIFICATION:

Please amend the specification as follows:

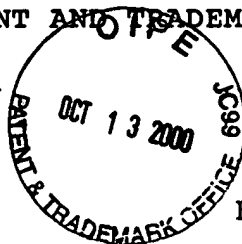
Page 4, line 11, delete "The prototype chip designed and fabricated contains connections pads for testing. The final chip ready for manufacture will not contain any connections pads and its size will be significantly reduced to $\leq 9 \text{ mm}^2$."

Page 7, line 10, delete "for this test version"

Page 7, line 18, delete "Eventually, the ID codes will" and substitute therefore ---The ID codes can---

Page 8, line 4, delete "cf." and substitute therefore ---see--

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OCT 19 2000
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